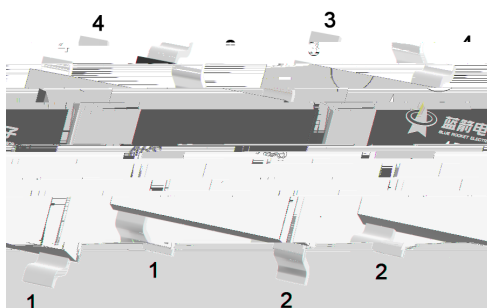
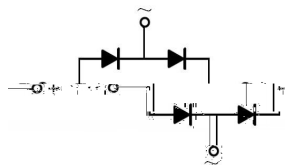


2.0A ABS/LBF
2.0A Surface Mount Glass Passivated Bridge Rectifier, ABS/LBF thin package.

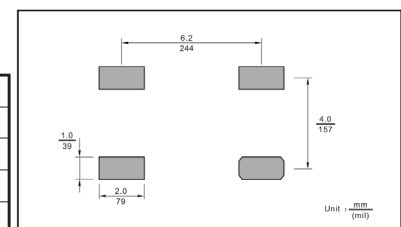
100V~1000V 2.0A
Glass Passivated Chip Junction,Reverse Voltage:100to1000V,Forward Current:2.0A,High Surge Current Capability,Designed for Surface Mount Application, Halogen free product.

General purpose.



PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)

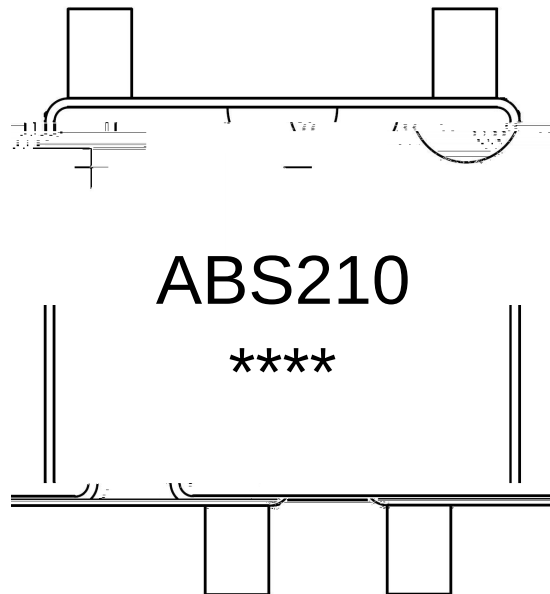
The recommended mounting pad size



See Marking Instructions.

Parameter	Symbol	Rating						Unit
		ABS201	ABS202	ABS204	ABS206	ABS208	ABS210	
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	100	200	400	600	800	1000	V
Maximum RMS Voltage	V _{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current at T _L = 100	I _o	2.0						A
Peak Forward Surge Current 8.3ms Single Half Sine Wave Superimposed on Rated Load(JEDEC Method)	I _{FSM}	60						A
Current Squared Time@1ms ≤ t 8.3ms T _a =25 Rating of per diode	I ² T	14.9						A ² Sec
Typical Junction Capacitance Note1	C _j	25						pF
Typical Thermal Resistance Note2	R _{JA}	65						/W
	R _{Jc}	20						

Operating and Storage Temperature Range , $-55^{\circ}C \sim 175^{\circ}C$

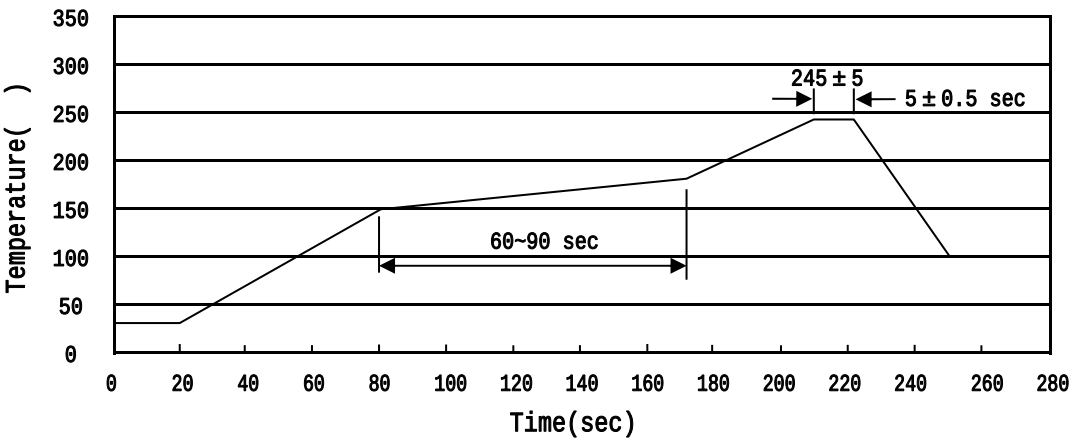


Note:

Product Type

Lot No. Code, code change with Lot No.

Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- 1

150 180

60 90sec;

1.Preheating:150~180 °C , Time:60~90sec.
- 2

245 5

5 0.5sec;

2.Peak Temp.:245 ± 5 °C , Duration:5 ± 0.5sec.
- 3

2 10 /sec.

3. Cooling Speed: 2~10 °C/sec.

260 ± 5

10 ± 1 sec.

Temp.:260±5

Time:10±1 sec

/ REEL

Package Type	Units					Dimension (unit mm ³)		
	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Boxes/Outer Box	Units/Outer Box	Reel	Inner Box	Outer Box
ABS/LBF	5,000	2	10,000	7	70,000	13 ×12	336X336X40	380X335X366